## PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company	life.augmented	STMicroelectronics International N.V
1.2 PCN No.		POWER AND DISCRETE PRODUCTS/24/15111
1.3 Title of PCN		Introduction of 8" Diode on STGHU30M65DF2AG.
1.4 Product Category		IGBT selected product
1.5 Issue date		2024-11-28

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	PIKE EMMA	
2.1.2 Phone	+44 1628896111	
2.1.3 Email	emma.pike@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Angelo RAO	
2.1.2 Marketing Manager	Giuseppe BAZZANO	
2.1.3 Quality Manager	Alfio PRIVITERA	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General	Wafer diameter modification	ST Tours for co-packaged diode

4. Description of change			
Old New			
4.1 Description	The IGBT STGHU30M65DF2AG is assembled with co-packaged Diode diffused on a 6" wafer.	The IGBT STGHU30M65DF2AG is assembled with co-packaged Diode diffused on a 8" wafer.	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Processability		

5. Reason / motivation for change	
5.1 Motivation	Capacity extension / Service improvement.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	New Dedicated FG and QA number

7. Timing / schedule		
7.1 Date of qualification results	2024-01-15	
7.2 Intended start of delivery	2025-05-26	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description 15111 RERPTD24003_1.0_1.0_Diode 8 inch wafer fab activation in Tours .pdf			
8.2 Qualification report and qualification results		Issue Date	2024-11-28

9. Attachments (additional documentations)	
15111 Public product.pdf 15111 RERPTD24003 1.0 1.0 Diode 8 inch wafer fab activation in Tours .pdf	

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No	
	STGHU30M65DF2AG		

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